

ABSTRACT OF THE DISCLOSURE

A method and apparatus for aligning a semiconductor device with a corresponding landing site on a carrier substrate. At least two apertures are formed in a semiconductor device, the apertures passing from a first major surface to a second, opposing major surface of the semiconductor device. Corresponding alignment features are provided on the carrier substrate at the landing site to which the device is to be mounted. The alignment features are aligned with the corresponding apertures to effect alignment of the device. The alignment features may include apertures corresponding in size, shape and arrangement to the semiconductor device apertures. An alignment pin may be placed through the two sets of apertures and to assist with alignment.

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